

DEM-SOT23LDO DEMONSTRATION FIXTURE

This User's Guide describes the characteristics, operation, and use of the DEM-SOT23LDO demonstration module (DEM).

1 Background

This DEM is designed to help the user easily evaluate and test the operation and functionality of Texas Instruments 5 and 6 lead SOT23 (DBV) package LDOs. This User's Guide includes setup instructions, a schematic diagram, and a PCB layout drawing for the DEM.

2 Setup

This DEM is specifically designed to be assembled with surface mount devices with footprints ranging from 603 to 1210. Additional holes have also been provided to accommodate leaded components. Refer to the product data sheet for specific guidelines when selecting components. For all designs, C1 and C2 are used as the input and output capacitors. Adjustable devices in the 5 lead packages use only R1 and R2. Refer to the typical application circuits in the product data sheet when populating the components. J5 is used to provide access to pin 4 for LDOs that feature a power good (PG) pin. The specific IC to be tested may be obtained through TI's sample program. All components other than the PWB are user supplied.

Figure 1 through Figure 3 show the board layout for the DEM-SOT23LDO printed circuit board.

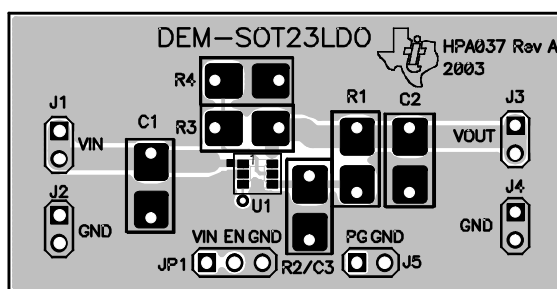


Figure 1. Assembly Layer

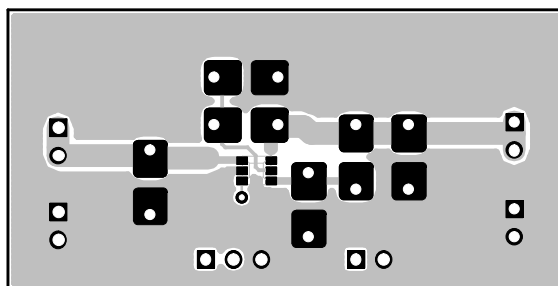


Figure 2. Top Layer Routing

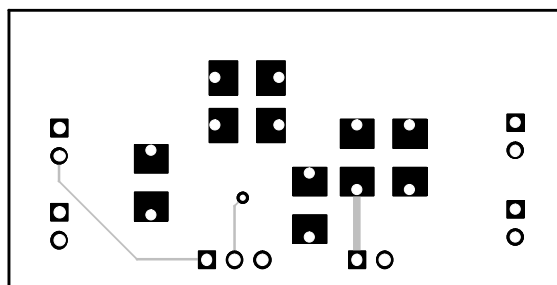


Figure 3. Bottom Layer Routing

3 Schematic

The circuit schematic in [Figure 4](#) shows the connections for all possible components for the six lead SOT23 package. Depending on the LDO being evaluated, some components may be omitted.

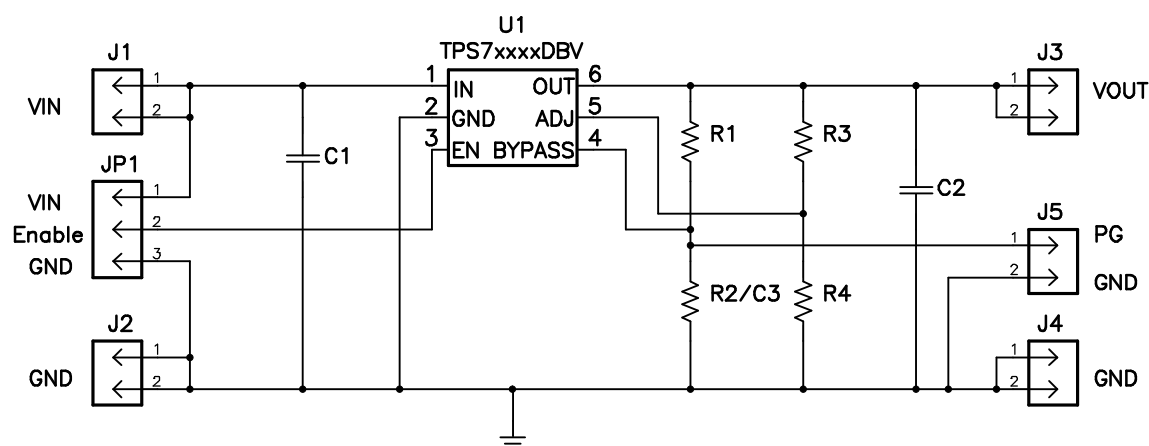


Figure 4. DEM-SOT23LDO Schematic

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